

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Serial No:

10/621.987

Docket No:

2011118

Filing Date: 07/16/2003

Applicant:

Jackson Hsieh

Examiner:

SOWARD, IDA M

Art Unit:

Title:

2822

SUBSTRATE STRUCTURE FOR AN INTEGRATED CIRCUIT PACKAGE

AND METHOD FOR MANUFACTURING THE SAME

To:

Commissioner for Patents

P.O. Box 1450

Alexandria, VA 22313-1450

RESPONSE TO OFFICE ACTION

Dear Sir:

. .

In response to the Office Action dated 03/12/2004, Applicant submits the following.

ELECTION

1. Applicant elects to restrict this application to the species designated by the Examiner as Species I, relating to Figs. 1-5, and directed to claims 1-3 and 5-6.

Respectfully submitted,

Date: April 13, 2004

PRO-TECHTOR INTERNATIONAL

Registration No: 32,737

Telephone: (408) 778-3440

20775 Norada Court

Saratoga, CA 95070-3018

CERTIFICATE OF MAILING (37 CFR 1.8a): I hereby certify that this paper (along with any referred to as being attached or enclosed) is being deposited with the United States Postal Service on the date shown below with sufficient postage as First Class Mail in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450.

Date: April 13, 2004